

Title (en)

METHOD FOR MAKING CONNECTION BALLS ON ELECTRONIC CIRCUITS OR COMPONENTS

Title (de)

HERSTELLUNGSVERFAHREN FÜR VERBINDUNGSKUGELN AUF SCHALTUNGEN ODER ELEKTRONISCHE BAUELEMENTE

Title (fr)

PROCEDE DE REALISATION DE BILLES DE CONNEXION SUR DES CIRCUITS OU DES COMPOSANTS ELECTRONIQUES

Publication

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Application

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Abstract (en)

[origin: FR2762715A1] The invention concerns a method for producing and soldering electrical connection balls (1) on mounting lands (2) for electronic circuit or component (3) electrical connection. The invention further concerns the device for implementing said method. The invention is characterised in that it essentially comprises the following steps: the operations for filling the stencil screen openings (4) by means of a squeegee (6) or the like and hot refusion are carried out with the stencil screen positioned above the substrate; the stencil screen (4) positioned on the component (3) during refusion is separated from the component after refusion but before the balls (1) are solidified, the latter being still in liquid state such that the balls that are being formed acquire their balanced position and their strictly identical spherical shape whatever their number; after the balls are solidified, the denatured binder is cleaned out.

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IPC 8 full level

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